



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-02-03
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LMV331ICT	EYW8*V331AAL	A	ZS1A	2013-04-02
Amount		UoM	Unit type	ST ECOPACK Grade
6.00		mg	Each	ECOPACK® 3

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOT	2X1.26X0.93	5	gull wing	
Comment	Package: SOT 323 5LDS			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-12 January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EYW8*V331AAL					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.385	mg	supplier	Silicon die	Silicon (Si)	7440-21-3		0.385	mg	1000000	64167
Leadframe	Copper & its alloys	2.563	mg	supplier	Alloy	Copper	7440-50-8		2.468	mg	962934	411333
Leadframe				supplier	Alloy	Iron	7439-89-6		0.058	mg	22630	9667
Leadframe				supplier	Alloy	Iron Phosphide(FeP)	26508-33-8		0.001	mg	390	167
Leadframe				supplier	Alloy	Zinc	7440-66-6		0.003	mg	1171	500
Leadframe				supplier	Alloy	Nickel	7440-02-0		0.029	mg	11315	4833
Leadframe				supplier	Alloy	Palladium	7440-05-3		0.003	mg	1171	500
Leadframe				supplier	Alloy	Gold	7440-57-5		0.001	mg	390	167
Die Attach	Other inorganic materials	0.02	mg	supplier	Glue	Epoxyde Bisphenol A Resin	25068-38-6		0.0018	mg	300000	1000
Die Attach				Supplier	Glue	Silica, vitreous	60676-86-0		0.0061	mg	200000	667
Die Attach				Supplier	Glue	Ethoxyethoxy-ethyl Acetate	112-15-2		0.0044	mg	200000	667
Die Attach				Supplier	Glue	Aluminium oxide	1344-28-1		0.004	mg	100000	333
Die Attach				Supplier	Glue	Bisphenol A diglycidyl ether polymer	25036-25-3		0.0028	mg	50000	167
Die Attach				Supplier	Glue	Glycol ether ester	Proprietary		0.0004	mg	50000	167
Die Attach			mg	Supplier	Glue	Diaminodiphenylsulfone	80-08-0		0.0004	mg	100000	333
Bonding wire	Copper & its alloys	0.03	mg	Supplier	Bonding wire	Gold (Au)	7440-57-5		0.03	mg	1000000	5000
Encapsulation	Other Organic Materials	3.002	mg	Supplier	Molding compound	Silica, vitreous	60676-86-0		2.582	mg	860093	430333
Encapsulation				Supplier	Molding compound	epoxy resin	25068-38-6		0.174	mg	57961	29000
Encapsulation				Supplier	Molding compound	Biphenyl epoxy resin	85954-11-6		0.15	mg	49967	25000
Encapsulation				Supplier	Molding compound	phenolic resin	29690-82-2		0.09	mg	29980	15000
Encapsulation				Supplier	Molding compound	carbon black	1333-86-4		0.006	mg	1999	1000